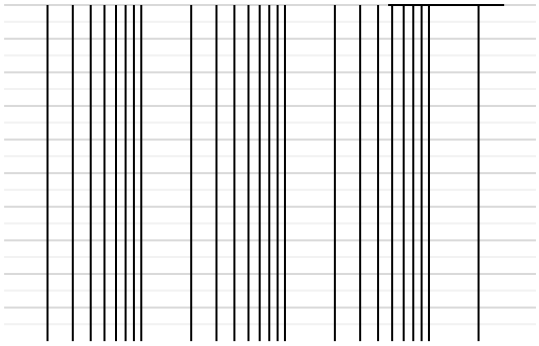
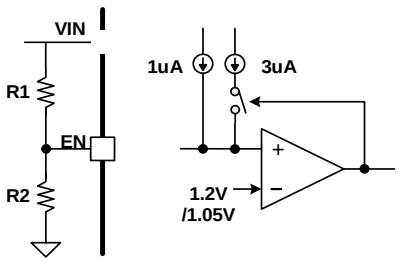
4.5V-60V Vin,

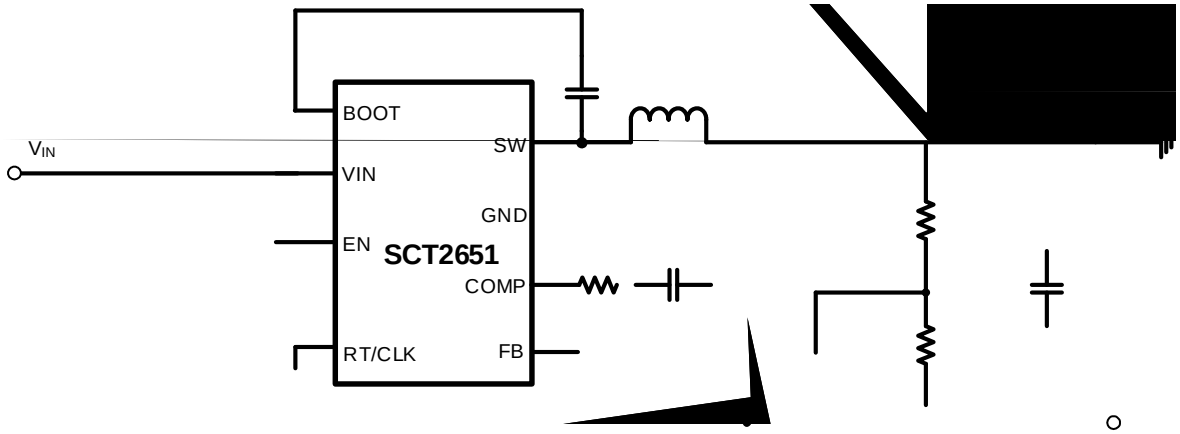
REVISION HISTORY

TYPICAL CHARACTERISTICS



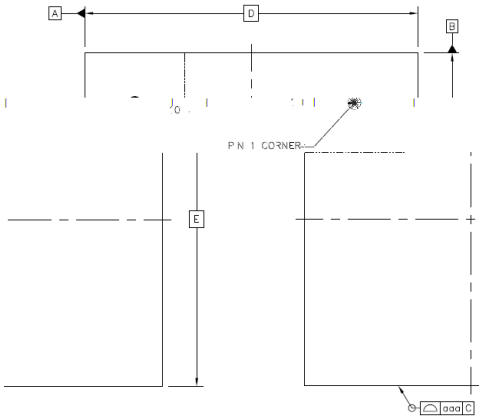
S U H

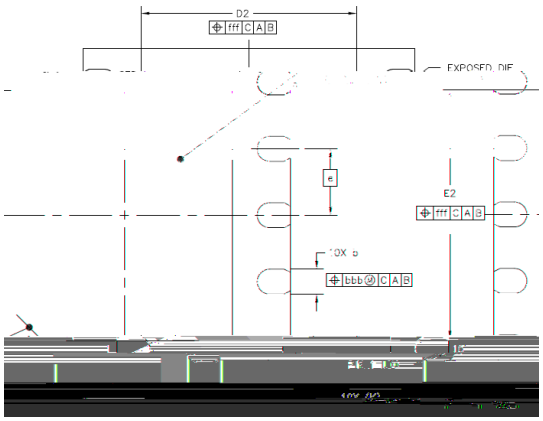

VIN
R1
EN
R2
1uA
3uA
+
–
1.2V
/1.05V

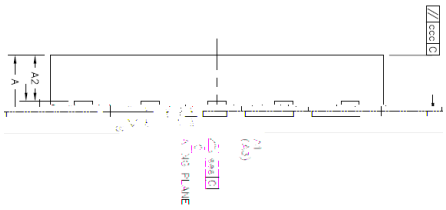

BOOT
VIN
SW
VIN
GND
EN
SCT2651
COMP
RT/CLK
FB

1.

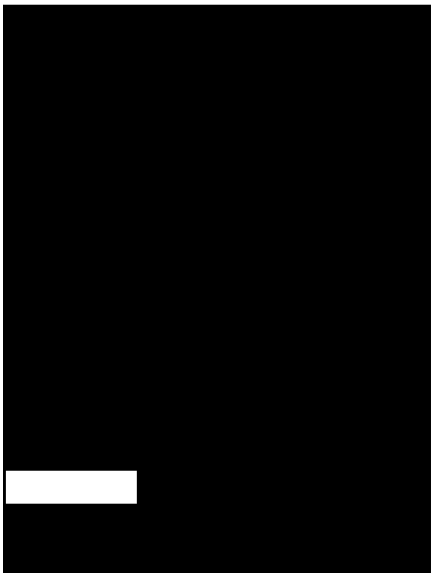
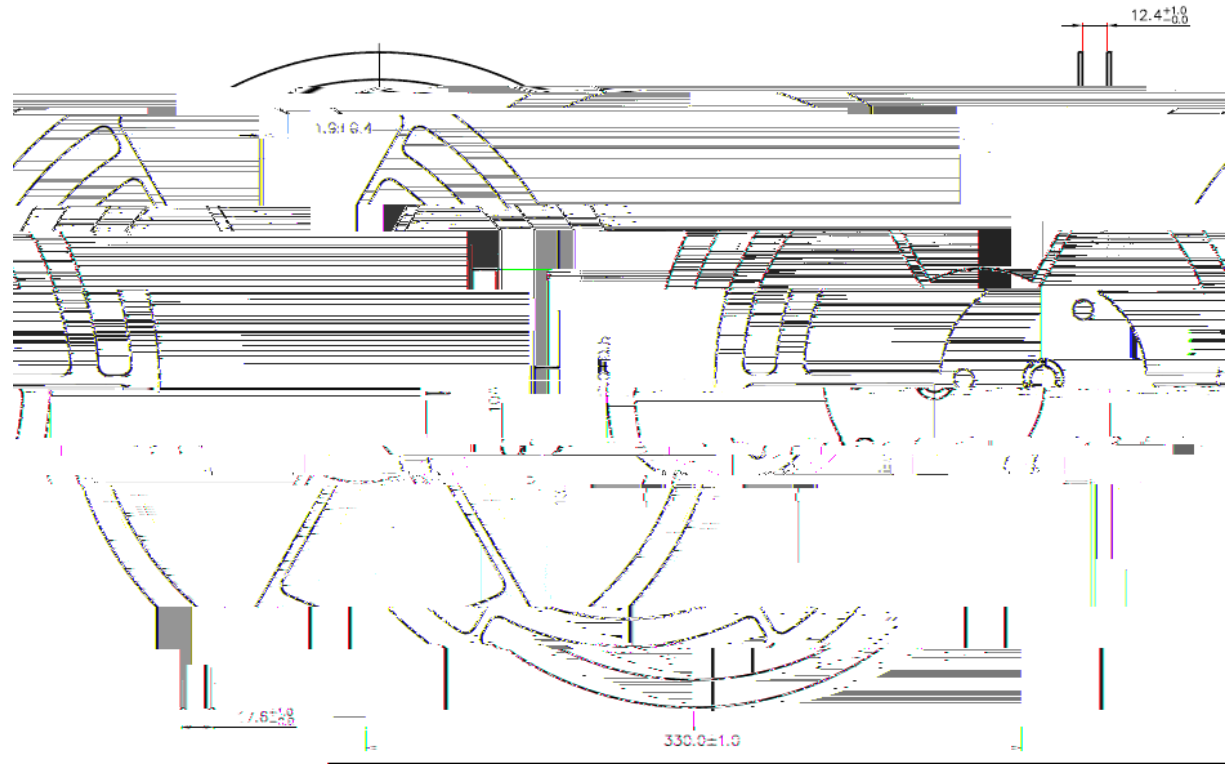
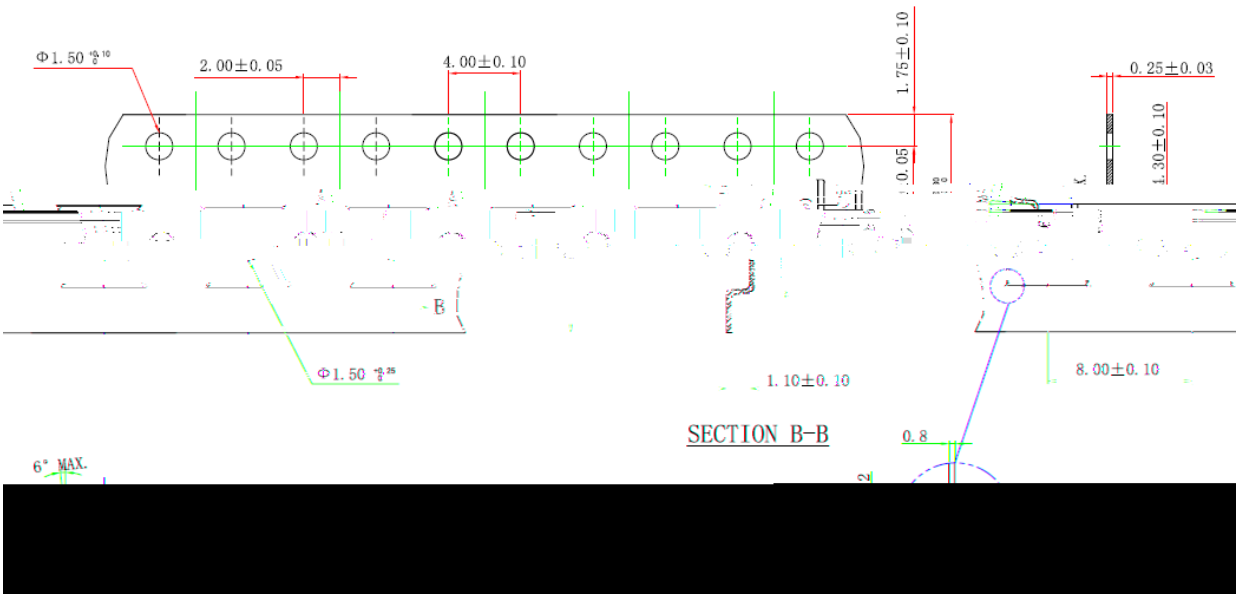
PACKAGE INFORMATION







1. Drawing proposed to be made a JEDEC package outline MO-220 variation.
2. Drawing not to scale.
3. All linear dimensions are in millimeters.
4. Thermal pad shall be soldered on the board.
5. Dimensions of exposed pad on bottom of package do not include mold flash.
6. Contact PCB board fabrication for minimum solder mask web tolerances between the pins.



TAPE AND REEL INFORMATION